Specification For Approval

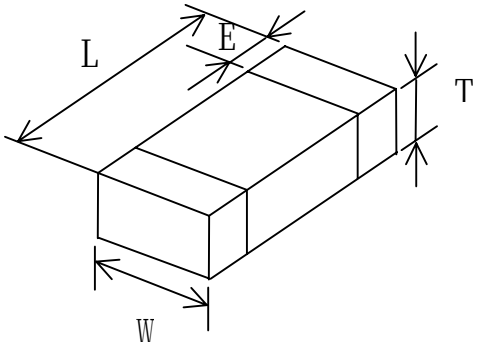
AXIS POWER 經軸電子

Multilayer chip bead 2012 (0805) series

PRODUCT DETAIL

Electrical Characteristics			Test Instruments
Z	Ω (Ref. Page 2)	TEST FREQ: 100 MHz TEST LEVEL: 250 mV	•HP4291B RF IMPEDANCE / MATERIAL ANALYZER •HP4338A/B MILLIOHMMETER •Agilent 8720ES S-PARAMETER NETWORK ANALYZER •HP6632B SYSTEM DC POWER SUPPLY
θ	NA		
SRF	NA		
DCR	Ω (Ref. Page 2)		
IDC	mA (Ref. Page 2)		

SHAPES AND DIMENSIONS



Unit : mm

TYPE	201209
L	2.0±0.2
W	1.25±0.2
T	0.9±0.2
E	0.5±0.3

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PART NUMBER AND CHARACTERISTICS TABLE
BCCB-2012E1 SERIES

Part No.	Impedance(Ω) +/- 25%	Test Freq.(MHz)	DCR(Ω) (Max.)	Rated Current (mA)
BCCB-2012E1-070T	7	100	0.15	600
BCCB-2012E1-110T	11	100	0.15	400
BCCB-2012E1-170T	17	100	0.15	400
BCCB-2012E1-260T	26	100	0.15	400
BCCB-2012E1-320T	32	100	0.15	400
BCCB-2012E1-390T	39	100	0.15	300
BCCB-2012E1-400T	40	100	0.10	600
BCCB-2012E1-600T	60	100	0.15	300
BCCB-2012E1-800T	80	100	0.15	300
BCCB-2012E1-101T	100	100	0.25	300
BCCB-2012E1-121T	120	100	0.25	300
BCCB-2012E1-151T	150	100	0.25	300
BCCB-2012E1-221T	220	100	0.30	200
BCCB-2012E1-301T	300	100	0.30	200
BCCB-2012E1-401T	400	100	0.30	200
BCCB-2012E1-601T	600	100	0.35	200
BCCB-2012E1-102T	1000	100	0.45	200
BCCB-2012E1-152T	1500	100	0.60	200
BCCB-2012E1-202T	2000	100	0.70	200
BCCB-2012E1-252T	2500	100	0.70	200

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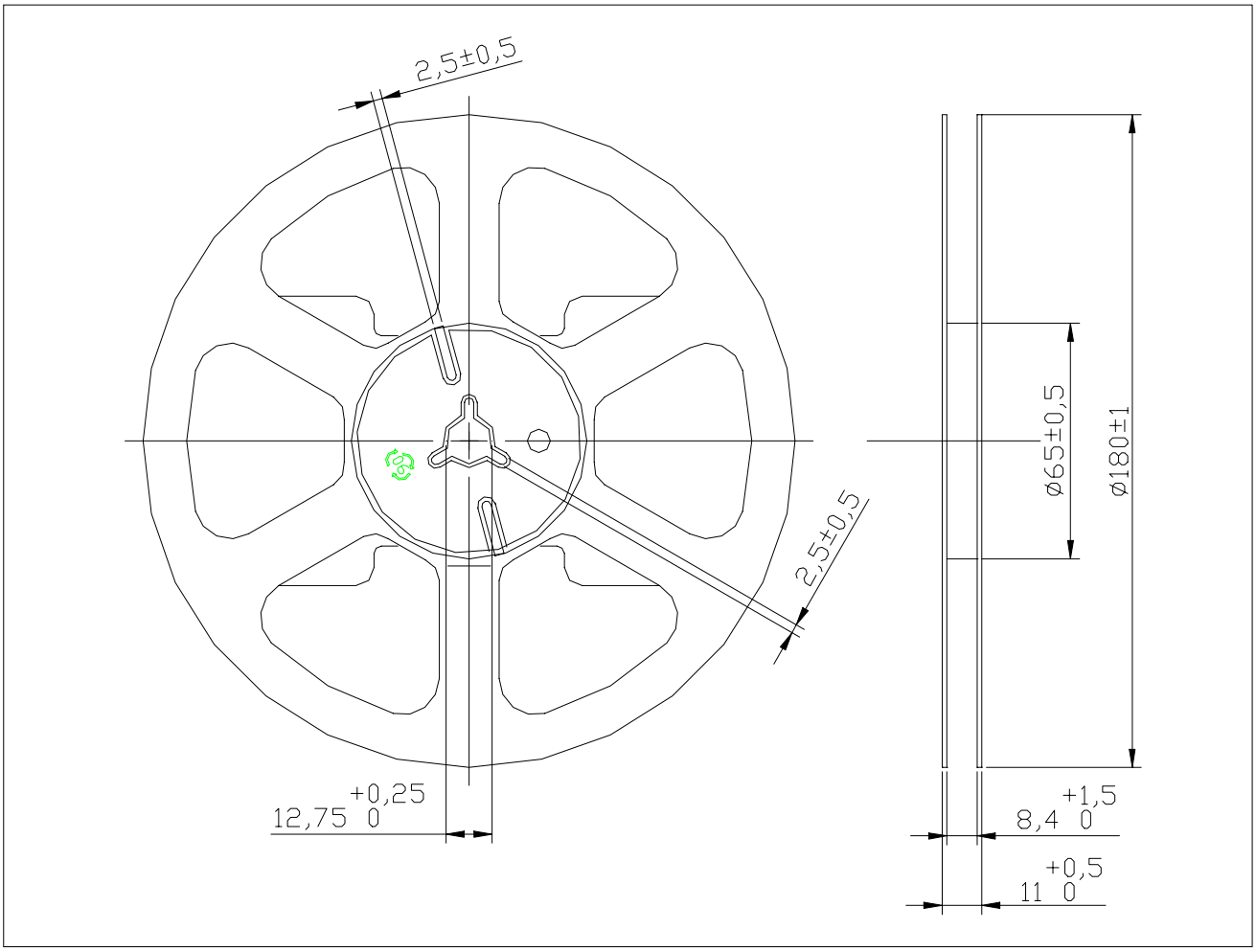
Multilayer chip bead 2012(0805) series

REEL DIMENSIONS

Unit: mm



Reel Packaging Quantity									
PART SIZE		**1005**	**1608**	**201209**	**201212**	**3216**	**3225**	**4516**	**4532**
7" REEL	Qty. (pcs)	10,000	4,000	4,000	3,000	3,000	2,000	2,000	1,000
13" REEL		NA	NA	10,000	10,000	10,000	5,000	5,000	2,500
BULK		20,000	20,000	20,000	20,000	20,000	10,000	10,000	10,000

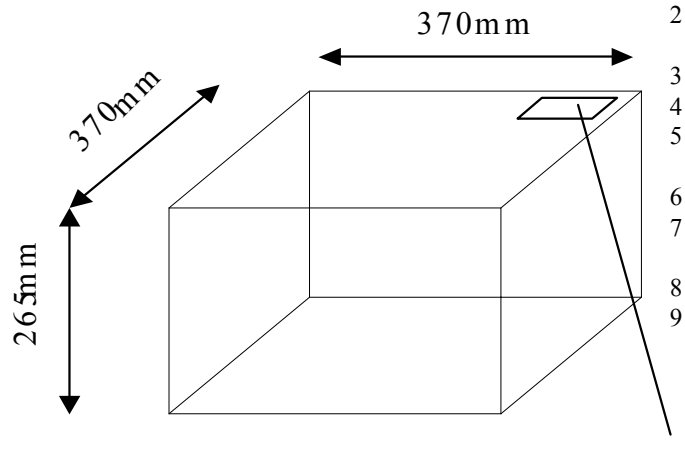
Specification For Approval

AXIS POWER 經軸電子

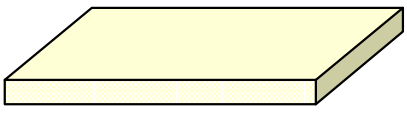
Multilayer chip bead 2012(0805) series

PACKING

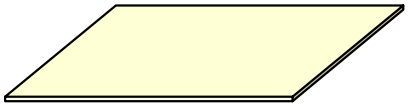
Carton size	L*W*H (mm)	Loading Quantity 7” (reels)	Loading quantity 13” (reels)
L	370*370*265	40	12
M	370*370*133	20	5
S	370*200*133	20	-



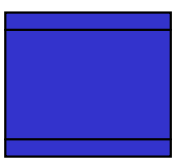
1. Put taped reel in an anti-static bag.
2. Put desiccant in an anti-static bag, and seal the anti-static bag by heat pressing.
3. Put the styrofoam in the bottom and around the box.
4. Put 4 reels which was packed as step 2 in one layer.
5. Then, put the stiffener on the top of those four reels as an isolation on between layer and layer.
6. Repeat step 4 and 5 until there is 10 layers in one box.
7. Before sealing the box, put the styrofoam on the top. Then, using adhesive tape to seal the box.
8. Stick the shipment label on the top of the box.
9. Recommended storage temperature:
   Temp : -40℃ to +85 ℃
   Humidity : 70% RH Max.



Styrofoam: × 6 (350mm*350mm*15mm)



Stiffener: × 10 (340*340mm)



Taped reel + desiccant + anti-static bag: × 40

Specification For Approval

AXIS POWER 經軸電子

Multilayer chip bead 2012(0805) series

RELIABILITY AND TEST CONDITION

Stress	Performance	Test Condition
Leaching	The chip should not crack ; More than 90% of the terminal electrode should be covered with solder , free from defects, chip body should not exposed.	1.Solder: Alpha Sn100 2.Solder Temp: 260 ±5℃ 3.Flux: Rosin 4.Dip time: 10 ±1 sec
Solderability 1 (IR Re-flow test)	1.Sn cover area need to over half thickness of chip 2.Chip shift distance under 50% of width 3.No short , open ,…etc defect symptom	1.Solder: M705-GRN360-K2-V Sn96.5/Ag3/Cu0.5 2.General:135/135/195/235℃ 3.100%TIN:155/155/220/265℃
Solderability 2	More than 90% of the terminal electrode should be covered with new solder	1.Solder: Alpha Sn100 2.Solder Temp.:230 ±5℃ 3.Flux: Rosin 4.Dip time: 4±1 sec
Terminal Strength	The terminal electrode should not break off nor the ferrite damaged	100505>0.2kgt, 160808>0.3kgt, 201209>0.6kgt, 201212>0.6kgt, 321611>1.0kgt, 322513>1.0kgt, 451616>1.0kgt, 453215>1.5kgt, CBA3216>1.2kgt ; pulling time:30 ±5 sec
Bending Strength	The ferrite should not be damaged by force applied on the right	100505>0.2kgf, 160808>0.3kgf, 201209>1.0kgf, 201212>1.0kgf, 321611>2.0kgf, 322513>2.5kgf, 451616>2.5kgf, 453215>2.5kgf, CBA3216>2.0kgf
Flexure Strength	No mechanical damage shall be noticed even when the board is bent 2 mm (0.079 inches)	1.At ambient temperature & Humidity 2.To bend 2 mm
Thermal Shock	1.No mechanical damage 2.Inductance should be within ±5% of the initial value 3.Q value should be within ±30% of the initial value 4.Impedance value should be	1.Temperature:-40 ~ 85℃ For 30 minutes each 2.Cycle: 100 cycles 3.Measurement: At ambient temperature 24 hours After test completion

Specification For Approval

AXIS POWER 經軸電子

Multilayer chip bead 2012(0805) series

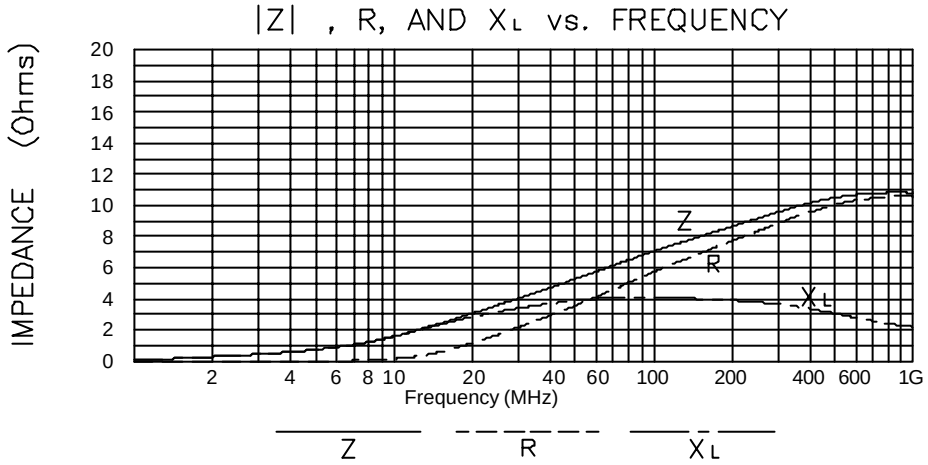
	within ±20% of the initial value	
Temperature Cycling	1.No mechanical damage 2.Inductance should be within ±5% of the initial value 3.Q value should be within ±30 % of the initial value 4.Impedance value should be within ±20% of the initial value	1. Temperature:-40~125 ℃ 2. Cycle: 100 cycles 3. Measurement: At ambient temperature 24 hours After test completion
Biased Humidity	1.No mechanical damage 2.Inductance should be within ±5% of the initial value 3.Q value should be within ±30 % of the initial value 4.Impedance value should be within ±20% of the initial value	1.Temperature: 40℃ 2.Humidity: 85 % RH 3.Applied current: Full rated current 4.Testing time: 1000 hrs 5. Measurement: At ambient temperature 24 hours After test completion
Rated Current	1.BCCB / BCCL / BCCLH product Surface temperature below room temperature plus 10 ℃ 2.High current DC power (ES) product surface temp. below room temperature plus 40 ℃	1.At ambient temperature & humidity 2.Testing time:5 minutes (under full rated current)

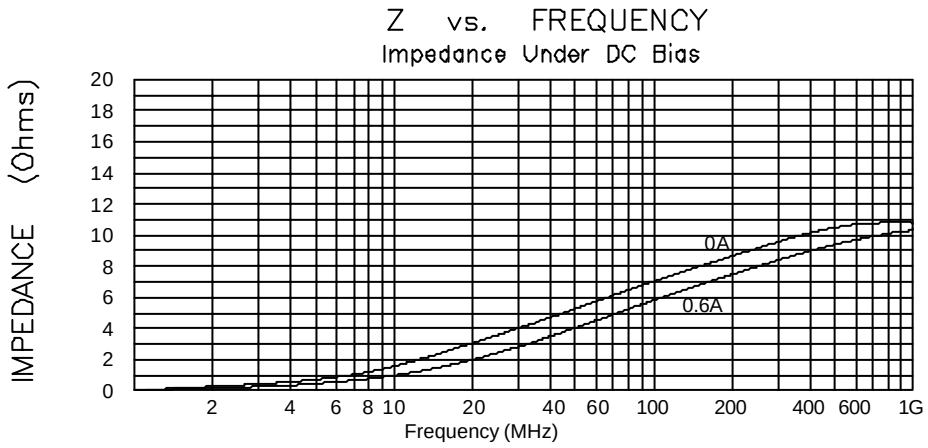
UNCONTROLLED DOCUMENT

BCCB-2012E1-070T

ELECTRICAL CHARACTERISTICS:

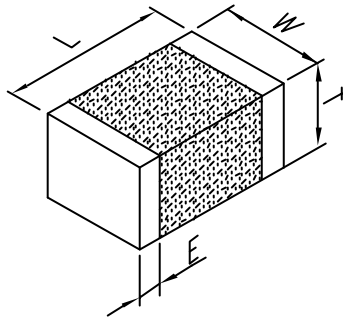
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	7		
Minimum	5.25		
Maximum	8.75	0.15	600mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

L 2.00(0.079) ±0.200(0.008)

W 1.25(0.049) ±0.200(0.008)

T 0.90(0.035) ±0.200(0.008)

E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

1.-All edges and corners must be rounded.

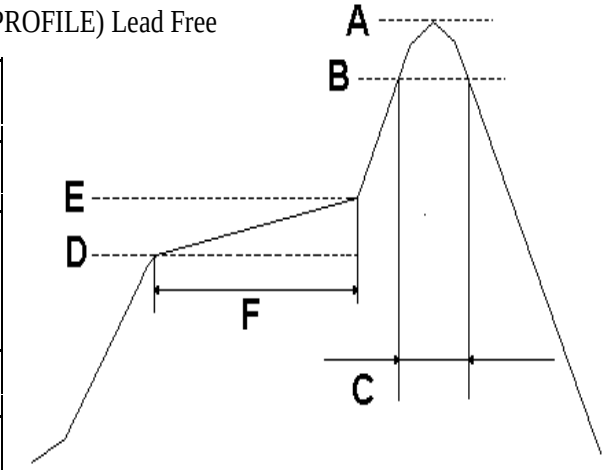
2.-Dimensions are in millimeters (inches)

3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260 ± 5℃*
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

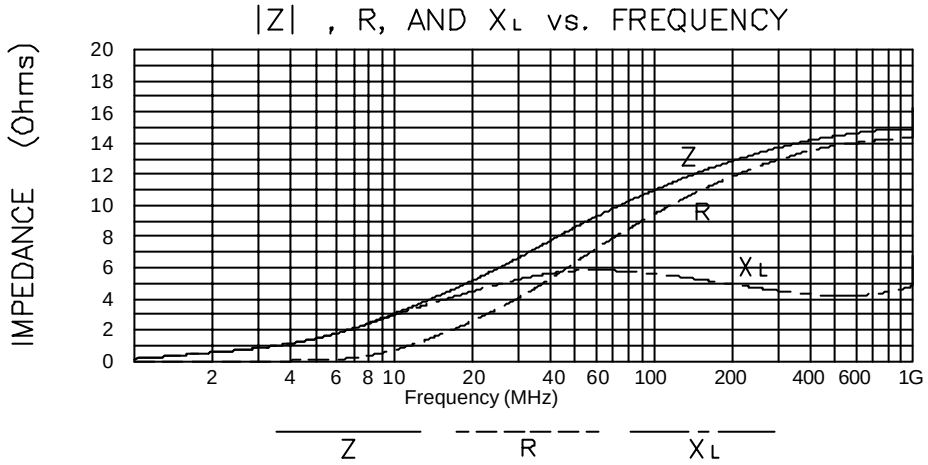


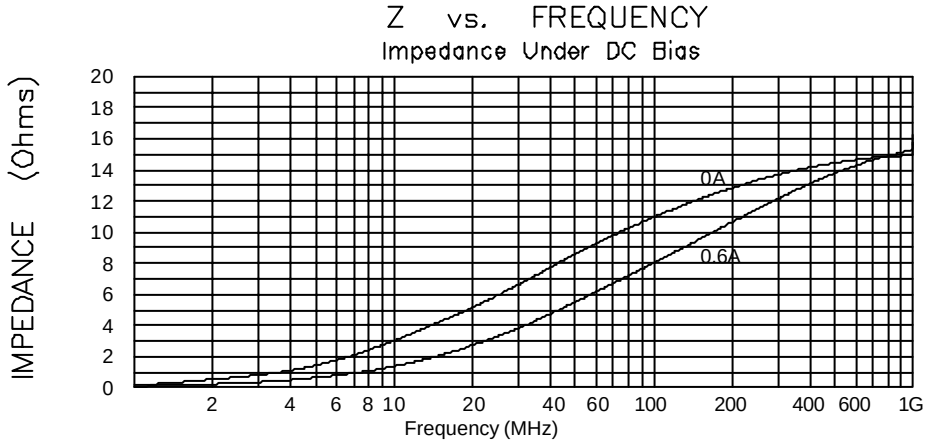
UNCONTROLLED DOCUMENT

BCCB-2012E1-110T

ELECTRICAL CHARACTERISTICS:

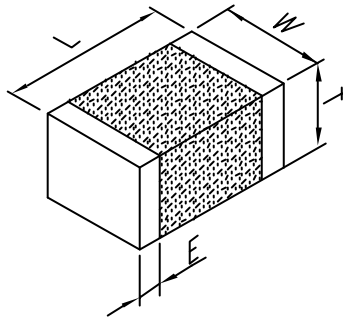
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	11		
Minimum	8.25		
Maximum	13.75	0.15	400mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

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W 1.25(0.049) ±0.200(0.008)
T 0.90(0.035) ±0.200(0.008)
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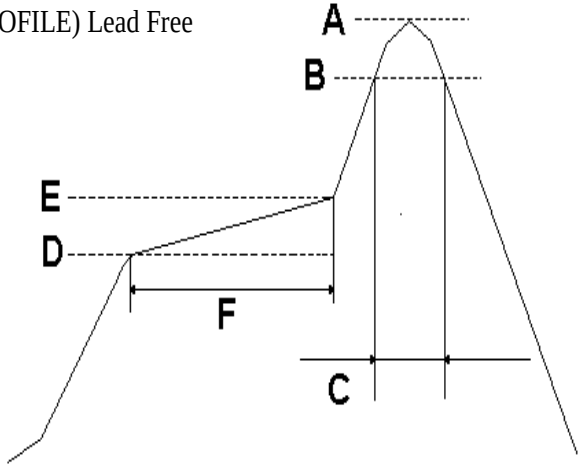
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

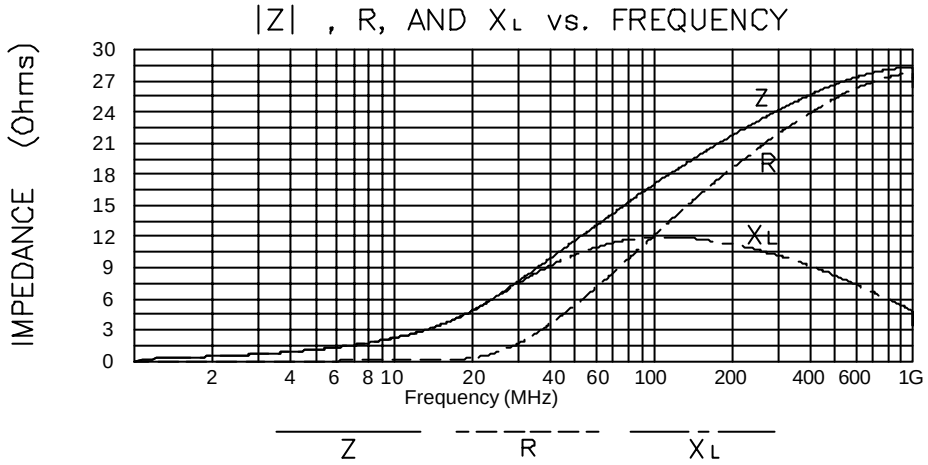


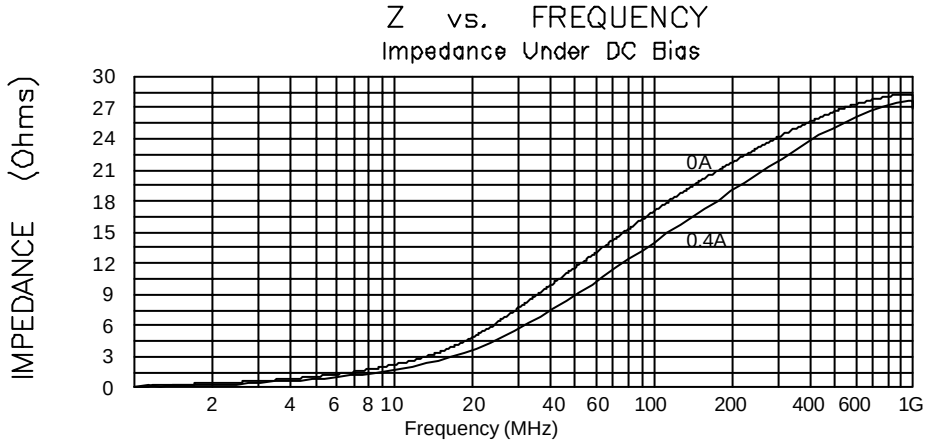
UNCONTROLLED DOCUMENT

BCCB-2012E1-170T

ELECTRICAL CHARACTERISTICS:

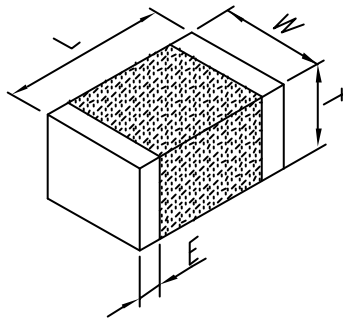
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	17		
Minimum	12.75		
Maximum	21.25	0.15	400mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



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W 1.25(0.049) ±0.200(0.008)
T 0.90(0.035) ±0.200(0.008)
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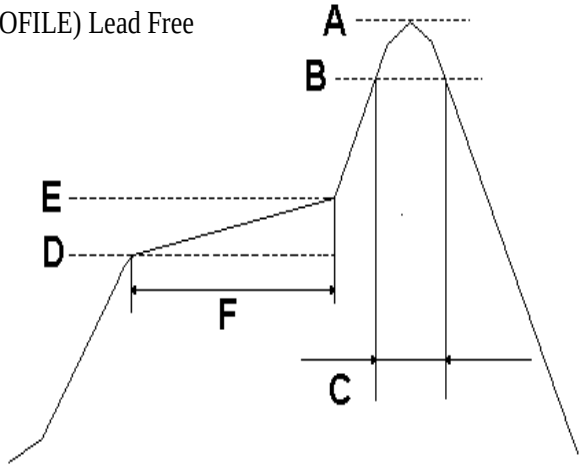
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

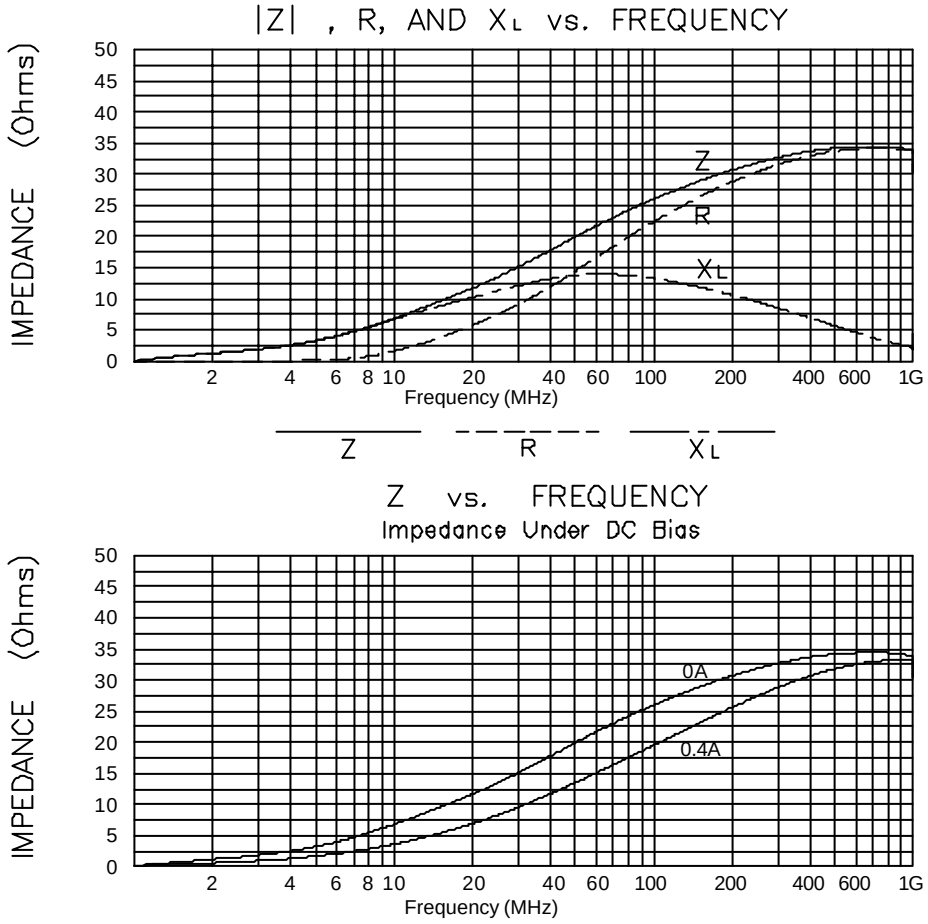


UNCONTROLLED DOCUMENT

BCCB-2012E1-260T

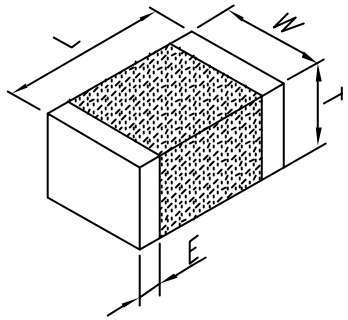
ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	26		
Minimum	19.5		
Maximum	32.5	0.15	400mA



Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



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T 0.90(0.035) ±0.200(0.008)
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A	260 ± 5℃
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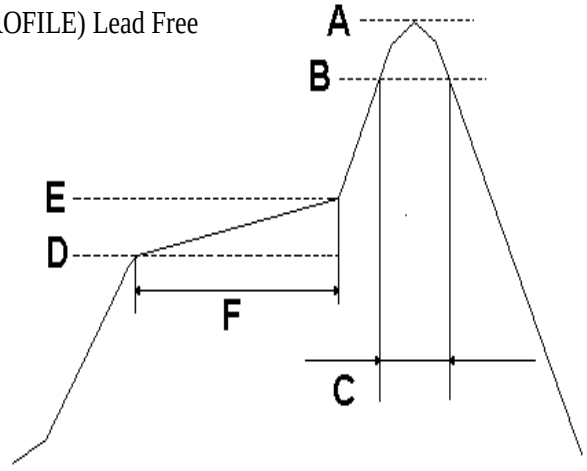
C	30±10sec
D	150℃
E	180℃
F	90±30sec

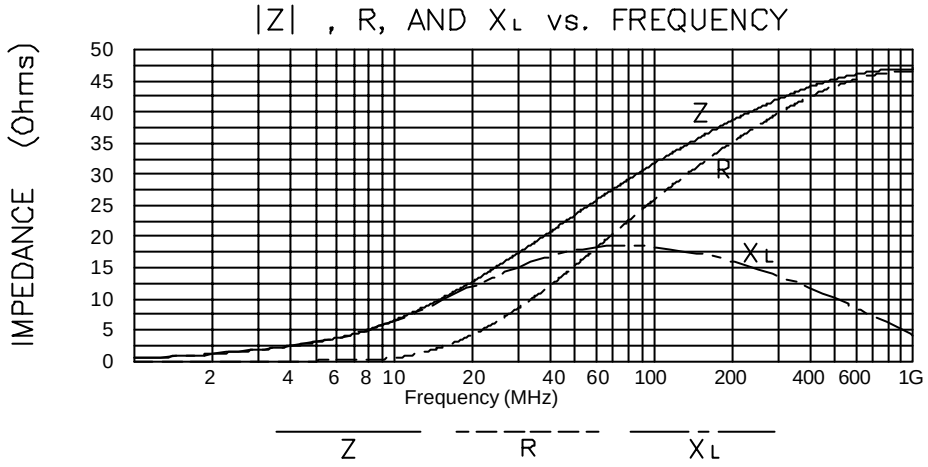


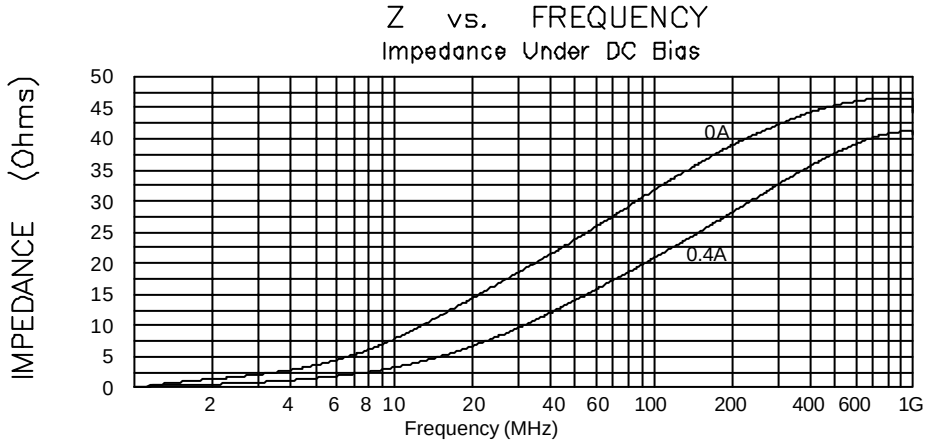
UNCONTROLLED DOCUMENT

BCCB-2012E1-320T

ELECTRICAL CHARACTERISTICS:

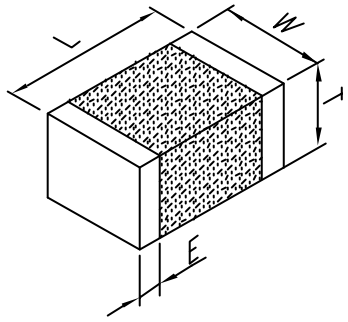
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	32		
Minimum	24		
Maximum	40	0.15	400mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



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E 0.50(0.020) ±0.300(0.012)

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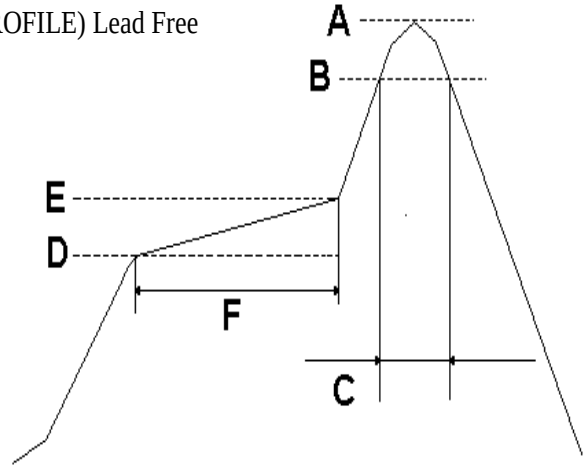
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

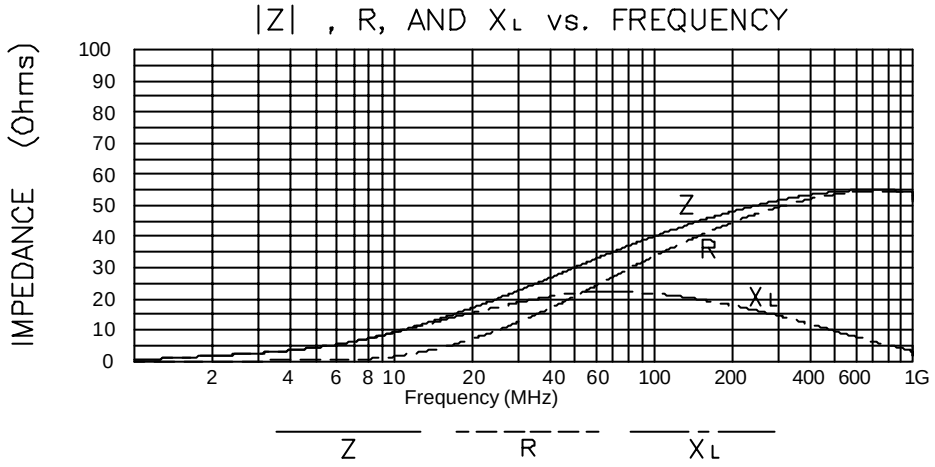


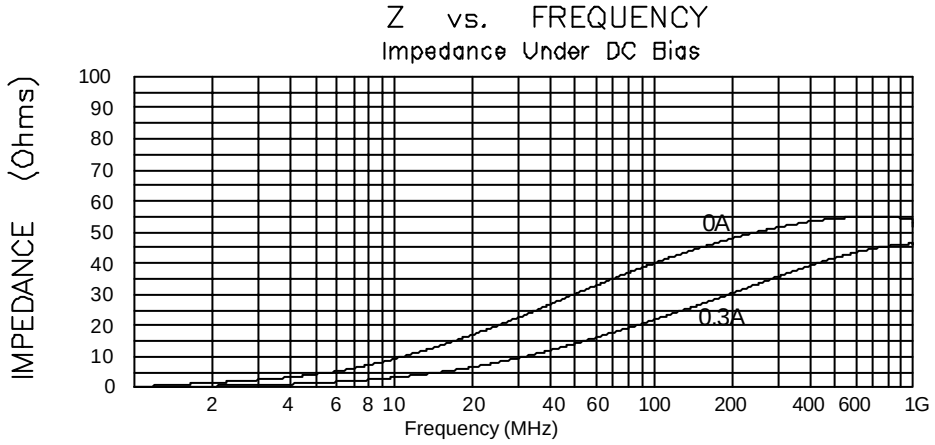
UNCONTROLLED DOCUMENT

BCCB-2012E1-390T

ELECTRICAL CHARACTERISTICS:

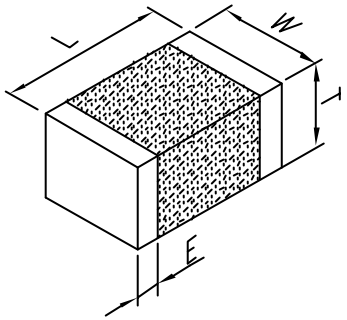
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	39		
Minimum	29		
Maximum	49	0.15	300mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

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W 1.25(0.049) ±0.200(0.008)

T 0.90(0.035) ±0.200(0.008)

E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

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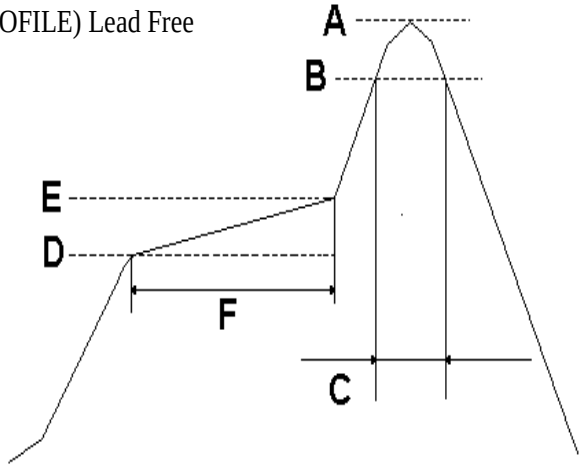
2.-Dimensions are in millimeters (inches)

3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260 ± 5℃*
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

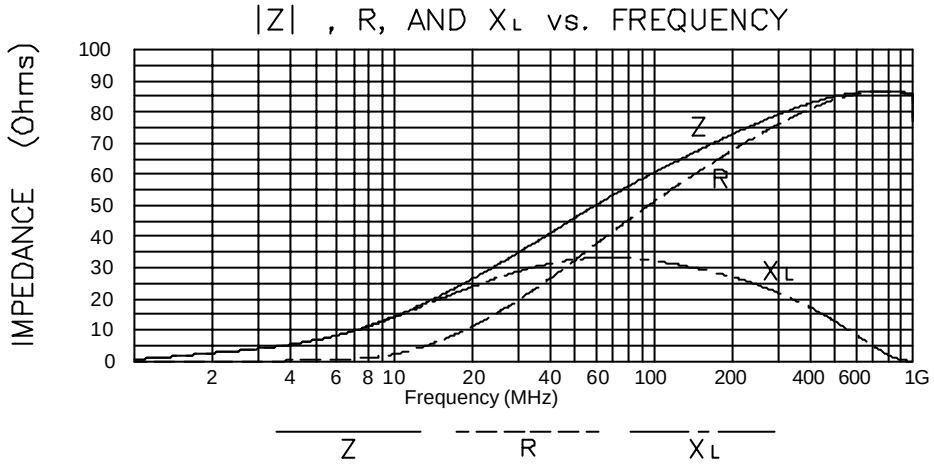


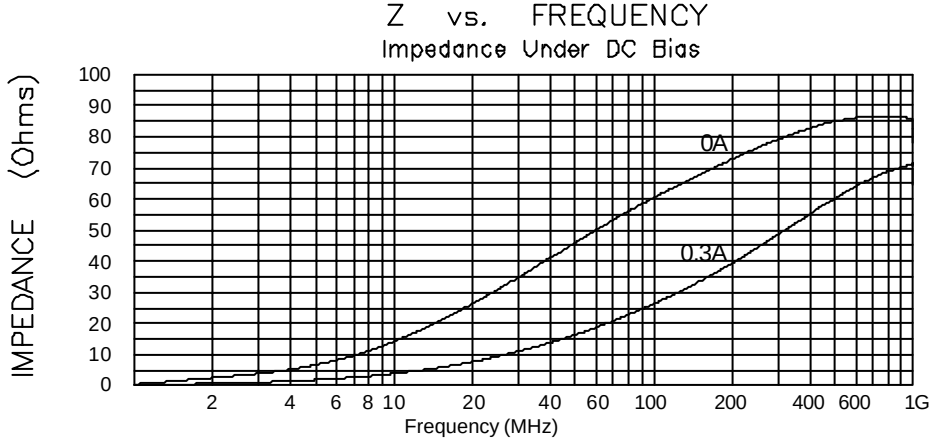
UNCONTROLLED DOCUMENT

BCCB-2012E1-600T

ELECTRICAL CHARACTERISTICS:

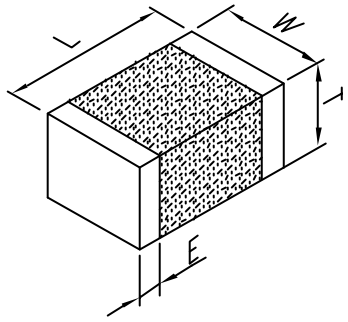
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	60		
Minimum	45		
Maximum	75	0.15	300mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

L 2.00(0.079) ±0.200(0.008)

W 1.25(0.049) ±0.200(0.008)

T 0.90(0.035) ±0.200(0.008)

E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

1.-All edges and corners must be rounded.

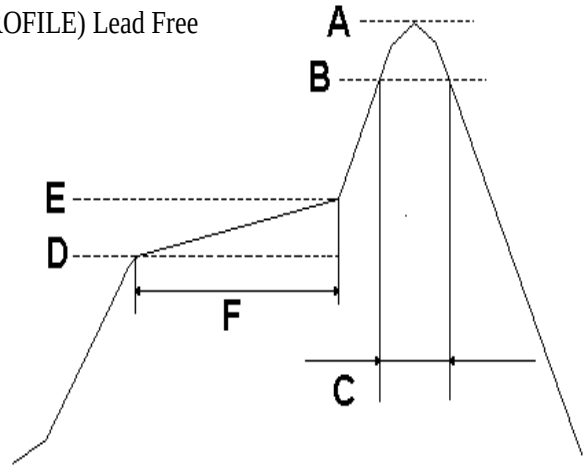
2.-Dimensions are in millimeters (inches)

3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260 ± 5℃*
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

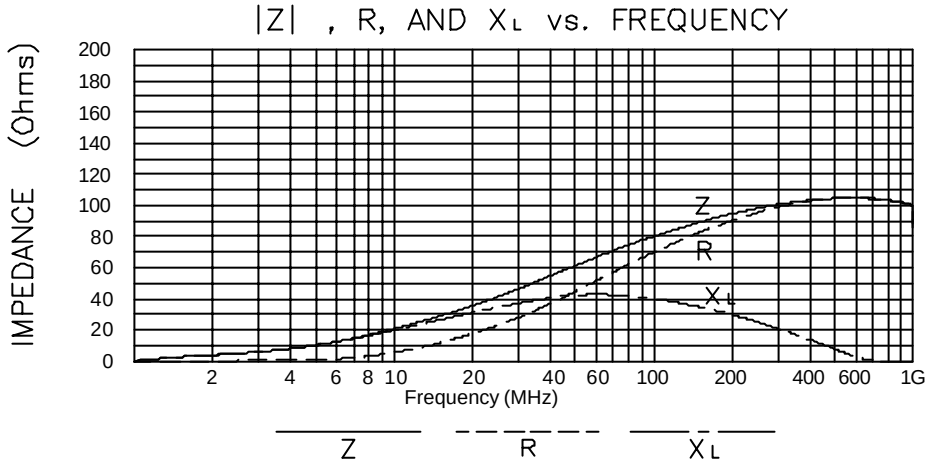


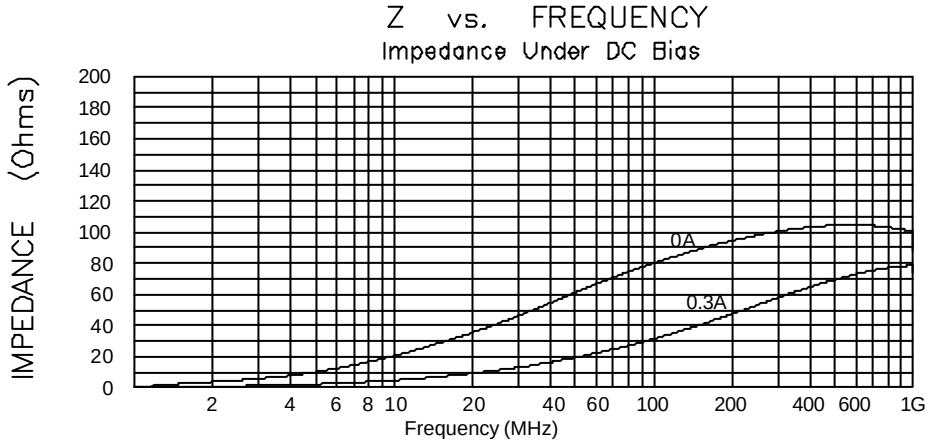
UNCONTROLLED DOCUMENT

BCCB-2012E1-800T

ELECTRICAL CHARACTERISTICS:

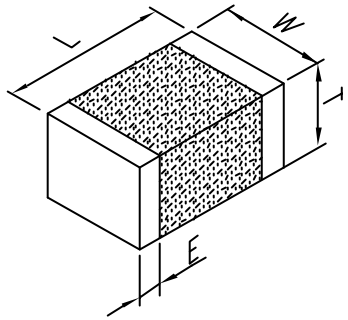
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	80		
Minimum	60		
Maximum	100	0.15	300mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

L 2.00(0.079) ±0.200(0.008)

W 1.25(0.049) ±0.200(0.008)

T 0.90(0.035) ±0.200(0.008)

E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

1.-All edges and corners must be rounded.

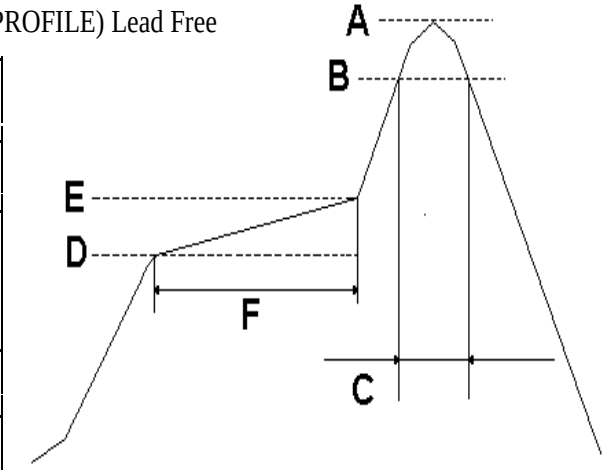
2.-Dimensions are in millimeters (inches)

3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260 ± 5℃*
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

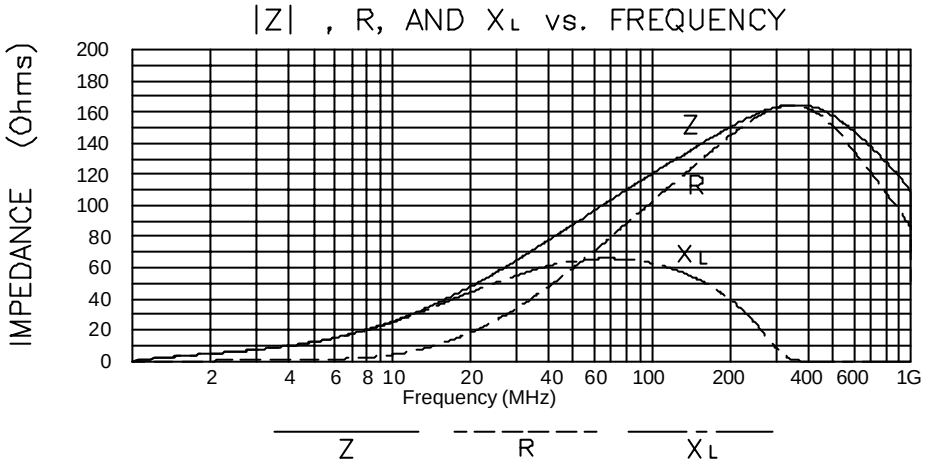


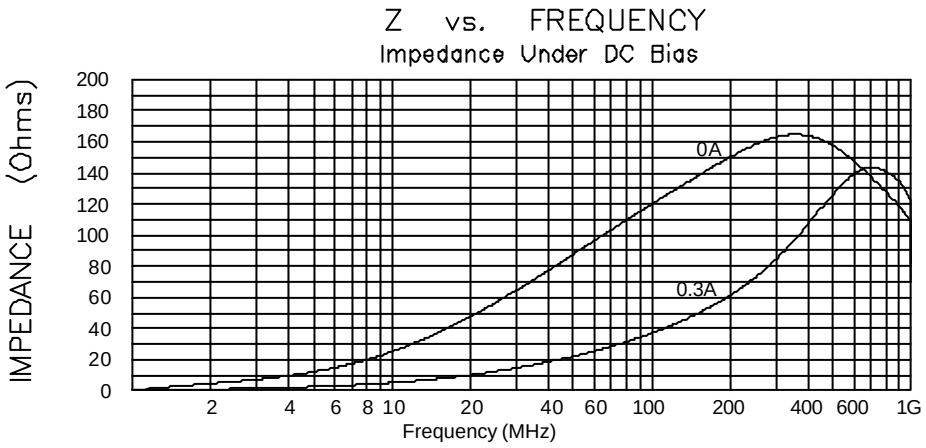
UNCONTROLLED DOCUMENT

BCCB-2012E1-121T

ELECTRICAL CHARACTERISTICS:

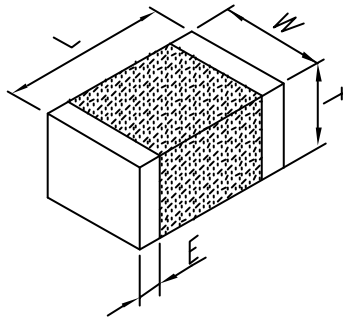
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	120		
Minimum	90		
Maximum	150	0.25	300mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

L 2.00(0.079) ±0.200(0.008)

W 1.25(0.049) ±0.200(0.008)

T 0.90(0.035) ±0.200(0.008)

E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

1.-All edges and corners must be rounded.

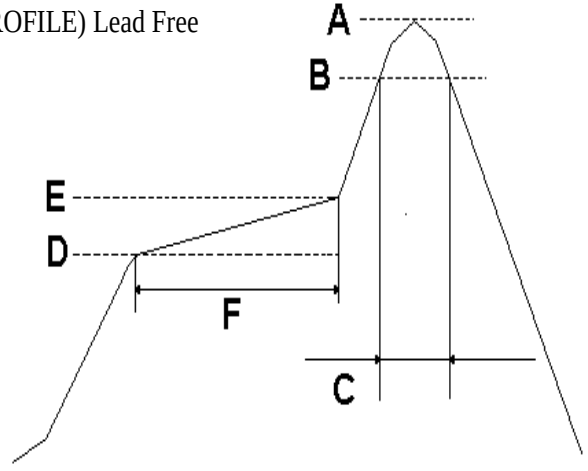
2.-Dimensions are in millimeters (inches)

3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260 ± 5℃*
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

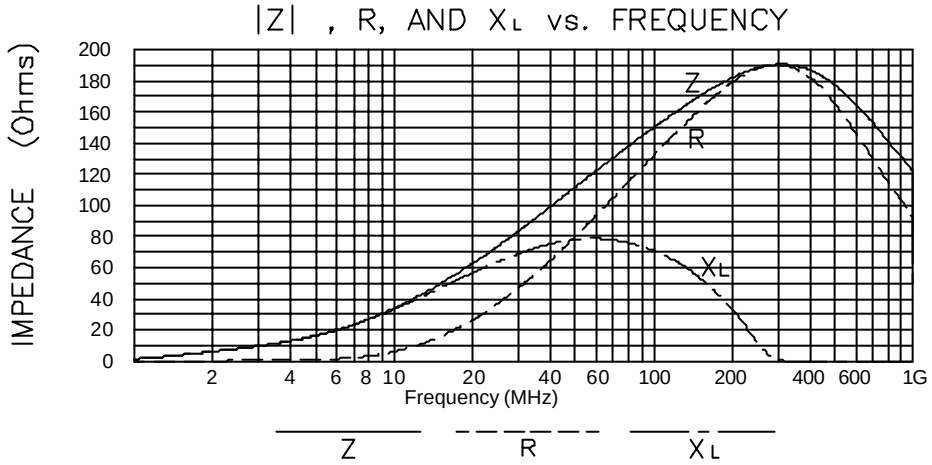


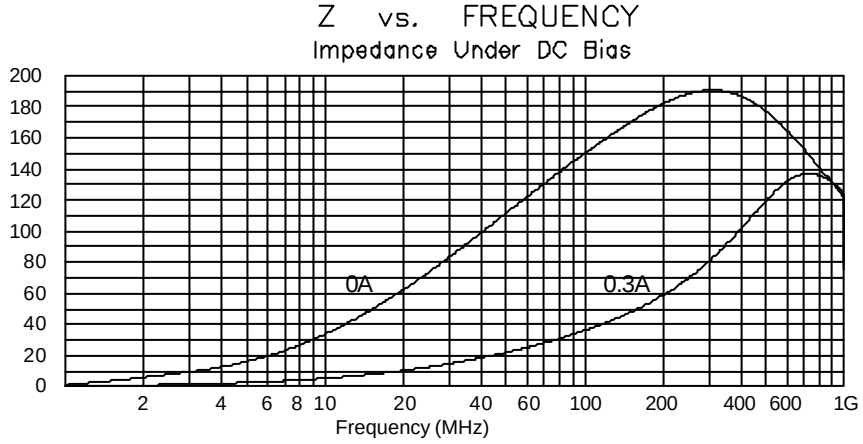
UNCONTROLLED DOCUMENT

BCCB-2012E1-151T

ELECTRICAL CHARACTERISTICS:

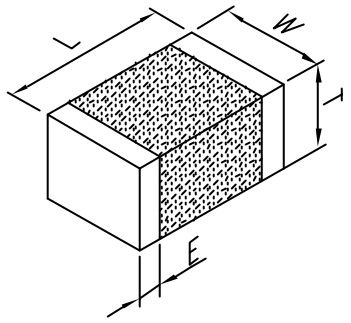
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	150		
Minimum	112.5		
Maximum	187.5	0.25	300mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

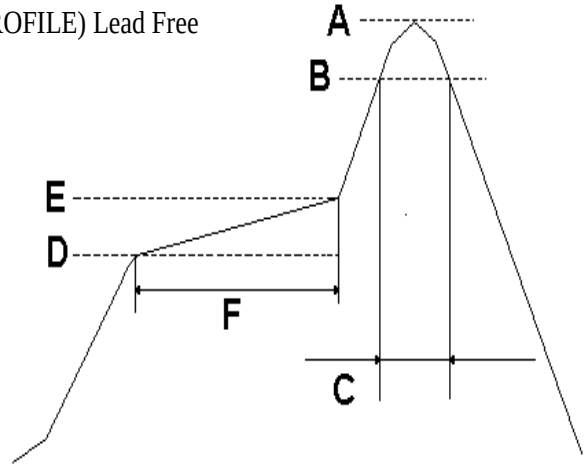
L 2.00(0.079) ±0.200(0.008)
W 1.25(0.049) ±0.200(0.008)
T 0.90(0.035) ±0.200(0.008)
E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED
1.-All edges and corners must be rounded.
2.-Dimensions are in millimeters (inches)
3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260±5℃*
B	*230±5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

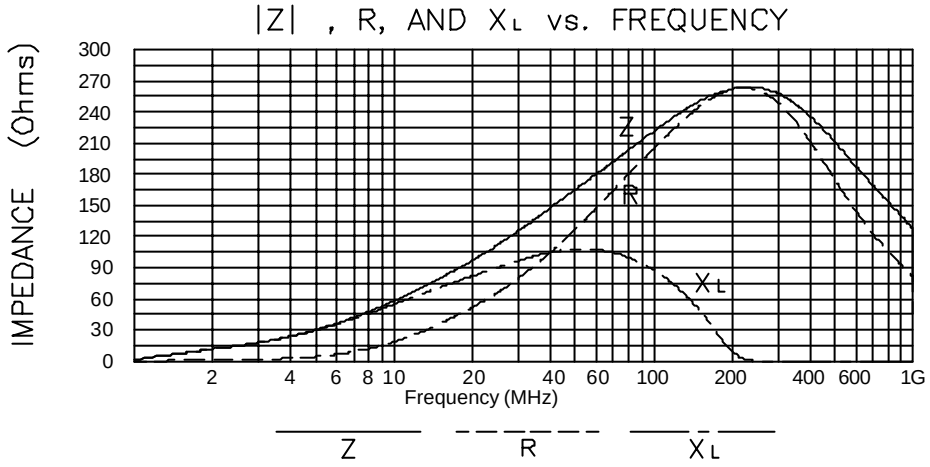


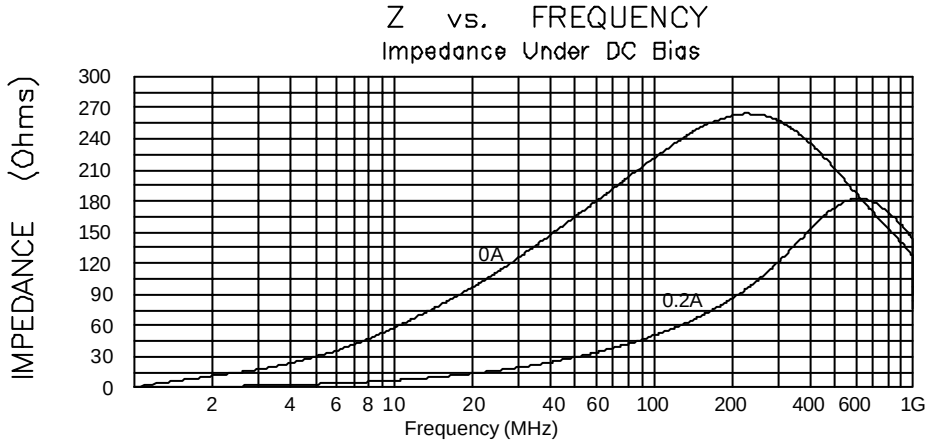
UNCONTROLLED DOCUMENT

BCCB-2012E1-221T

ELECTRICAL CHARACTERISTICS:

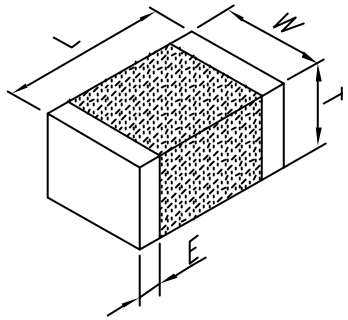
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	220		
Minimum	165		
Maximum	275	0.30	200mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

L 2.00(0.079) ±0.200(0.008)

W 1.25(0.049) ±0.200(0.008)

T 0.90(0.035) ±0.200(0.008)

E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

1.-All edges and corners must be rounded.

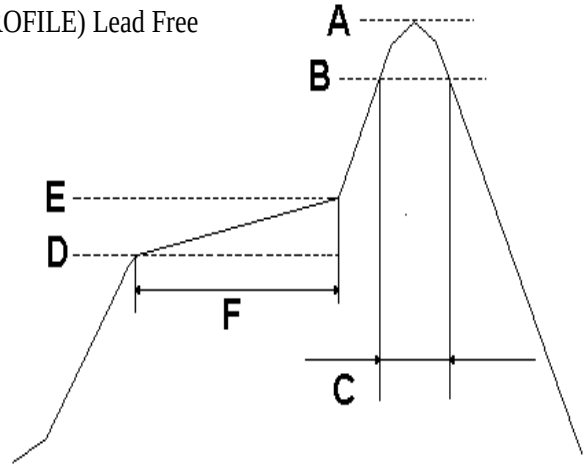
2.-Dimensions are in millimeters (inches)

3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260±5℃*
B	*230±5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

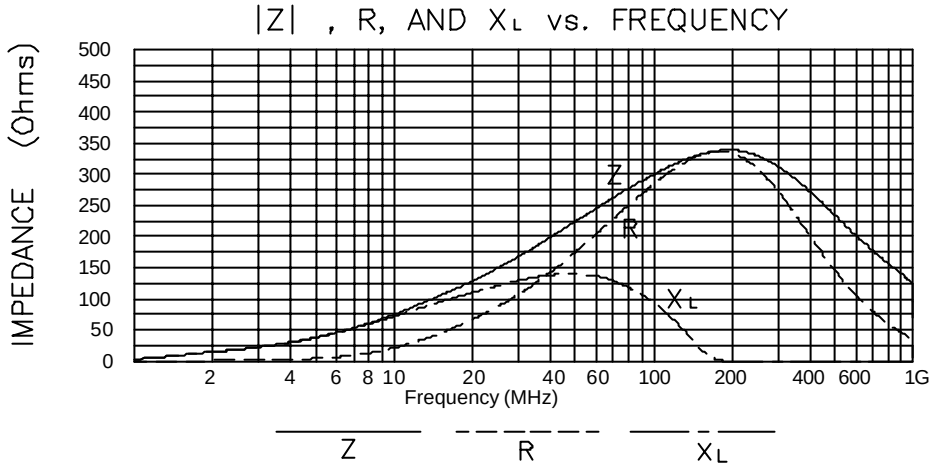


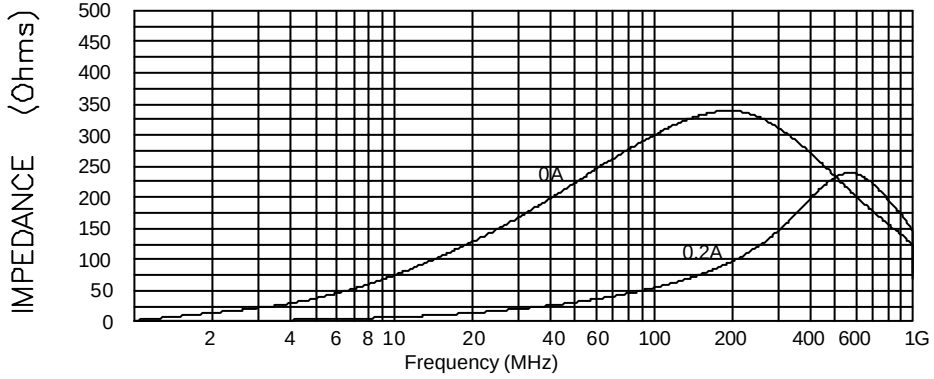
UNCONTROLLED DOCUMENT

BCCB-2012E1-301T

ELECTRICAL CHARACTERISTICS:

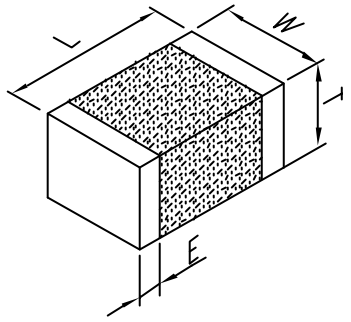
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	300		
Minimum	225		
Maximum	375	0.30	200mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

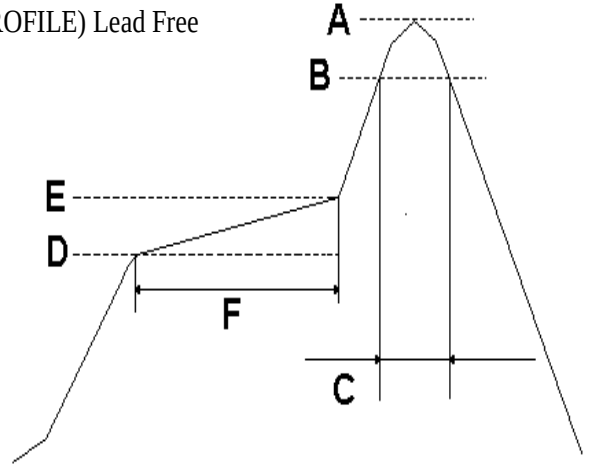
L 2.00(0.079) ±0.200(0.008)
W 1.25(0.049) ±0.200(0.008)
T 0.90(0.035) ±0.200(0.008)
E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED
1.-All edges and corners must be rounded.
2.-Dimensions are in millimeters (inches)
3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260 ± 5℃*
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

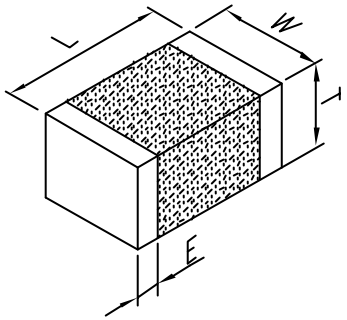


UNCONTROLLED DOCUMENT

BCCB-2012E1-401T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	400		
Minimum	300		
Maximum	500	0.3	200mA



PHYSICAL DIMENSIONS:

L 2.00(0.079) ±0.200(0.008)

W 1.25(0.049) ±0.200(0.008)

T 0.90(0.035) ±0.200(0.008)

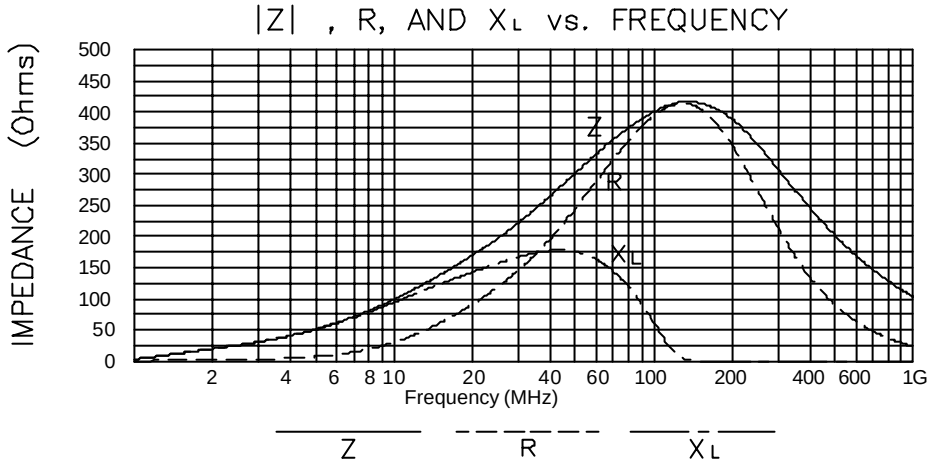
E 0.50(0.020) ±0.300(0.012)

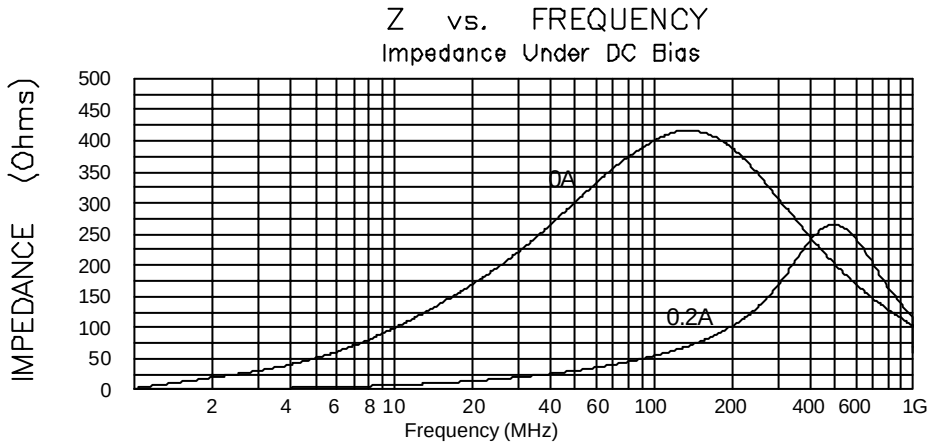
NOTES: UNLESS OTHERWISE SPECIFIED

1.-All edges and corners must be rounded.

2.-Dimensions are in millimeters (inches)

3.-Taped and Reeled per current EIA specification.





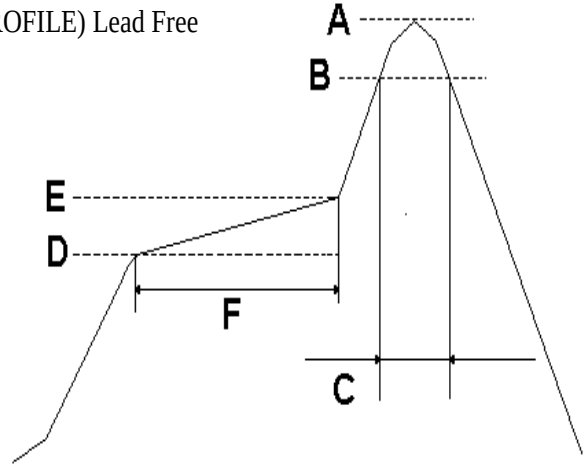
Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260 ± 5℃*
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

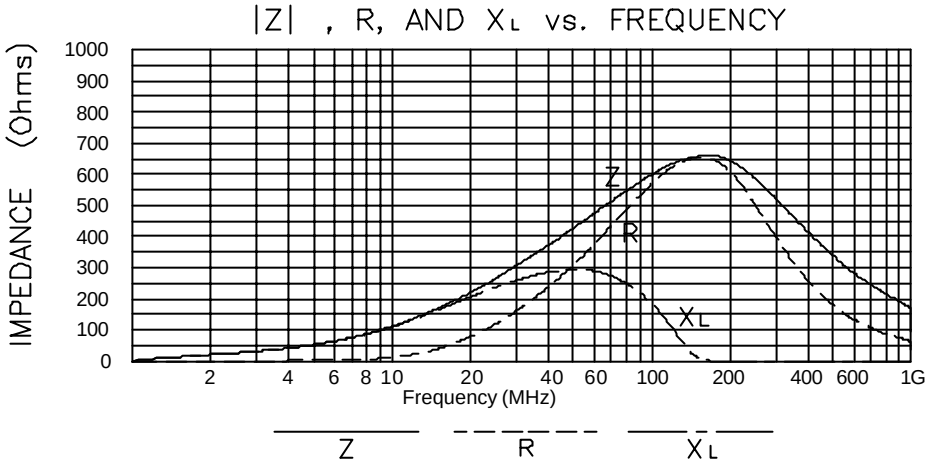


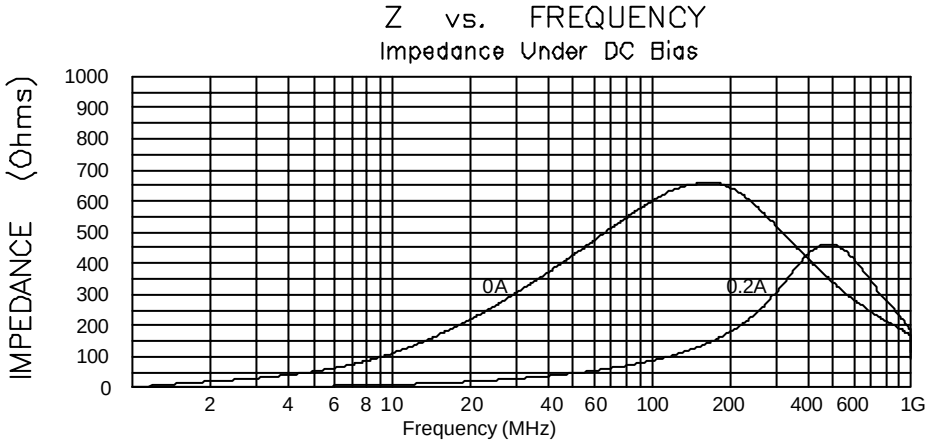
UNCONTROLLED DOCUMENT

BCCB-2012E1-601T

ELECTRICAL CHARACTERISTICS:

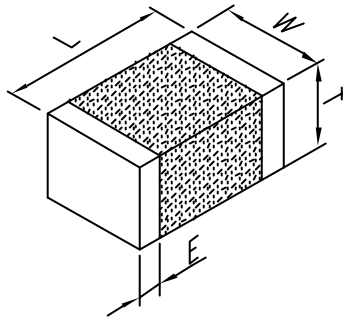
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	600		
Minimum	450		
Maximum	750	0.35	200mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

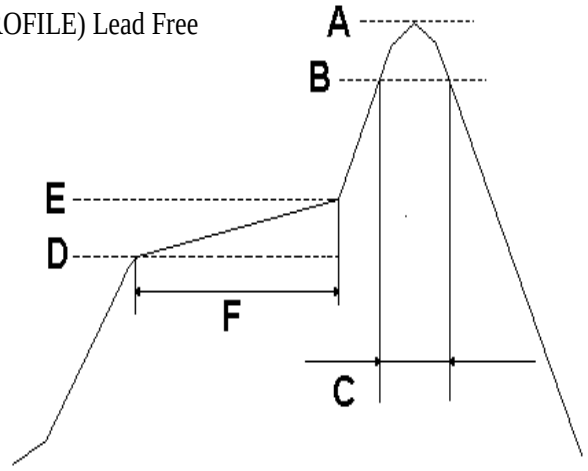
L 2.00(0.079) ±0.200(0.008)
W 1.25(0.049) ±0.200(0.008)
T 0.90(0.035) ±0.200(0.008)
E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED
1.-All edges and corners must be rounded.
2.-Dimensions are in millimeters (inches)
3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260 ± 5℃*
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

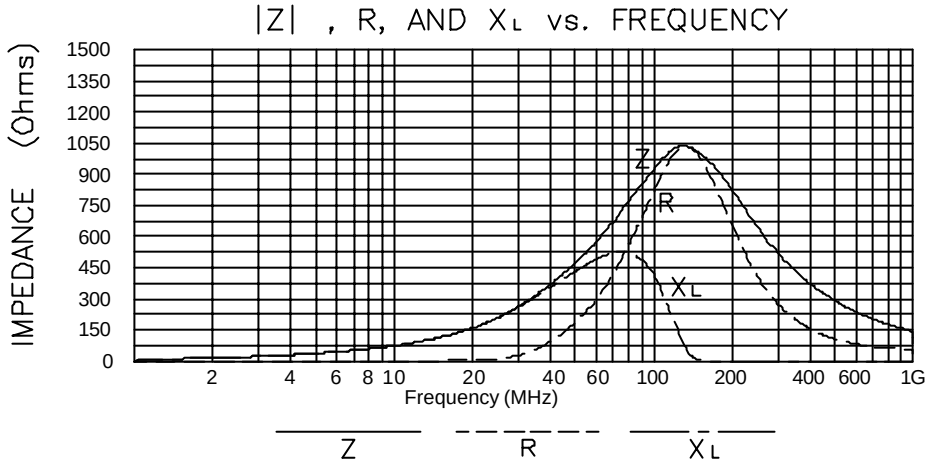


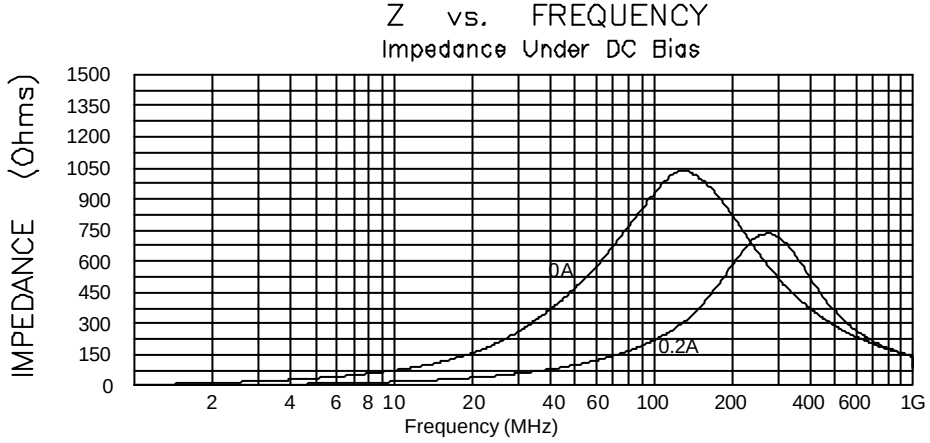
UNCONTROLLED DOCUMENT

BCCB-2012E1-102T

ELECTRICAL CHARACTERISTICS:

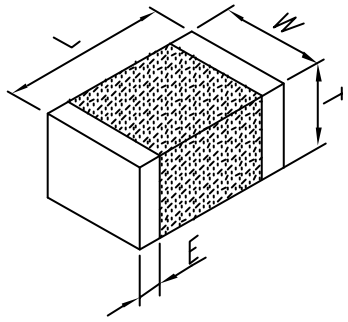
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	1000		
Minimum	750		
Maximum	1250	0.45	200mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

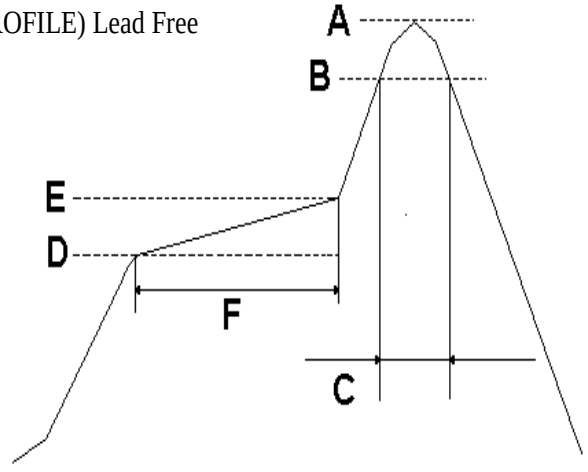
L 2.00(0.079) ±0.200(0.008)
W 1.25(0.049) ±0.200(0.008)
T 0.90(0.035) ±0.200(0.008)
E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED
1.-All edges and corners must be rounded.
2.-Dimensions are in millimeters (inches)
3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260±5℃*
B	*230±5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

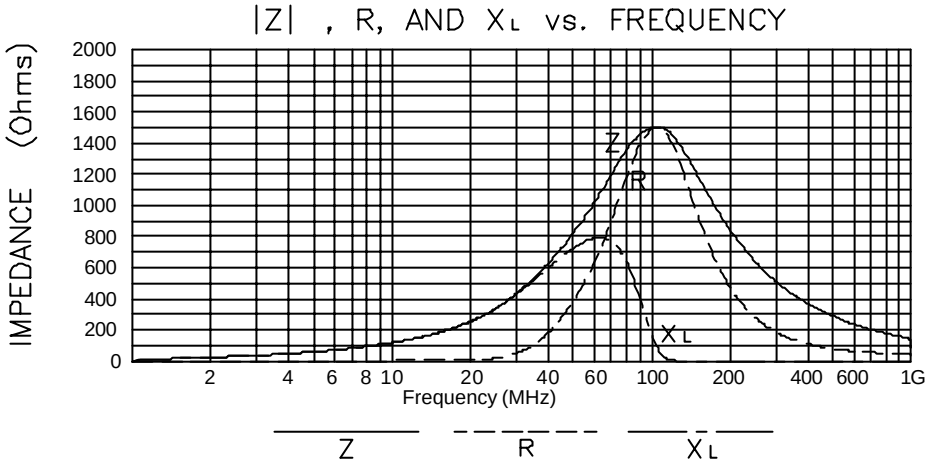


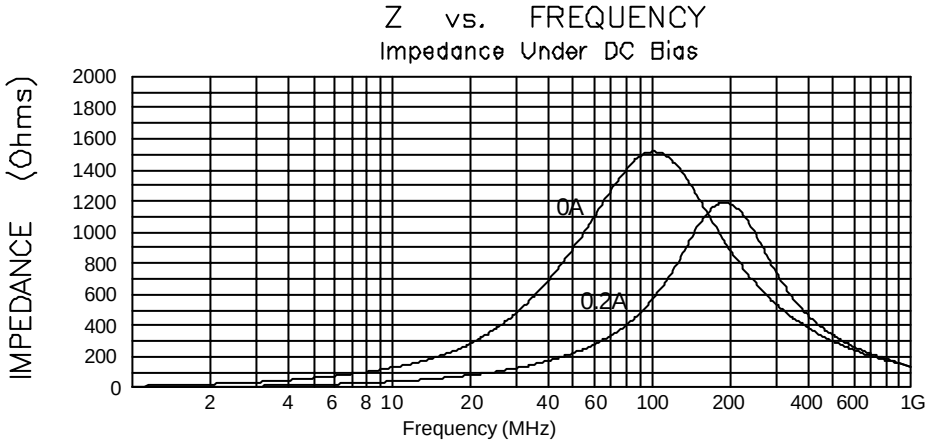
UNCONTROLLED DOCUMENT

BCCB-2012E1-152T

ELECTRICAL CHARACTERISTICS:

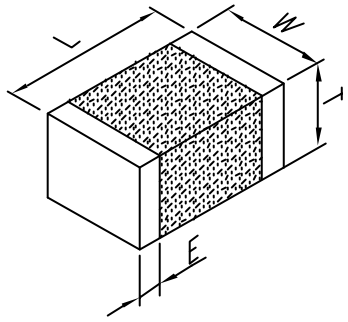
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	1500		
Minimum	1125		
Maximum	1875	0.60	200mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

L 2.00(0.079) ±0.200(0.008)
W 1.25(0.049) ±0.200(0.008)
T 0.90(0.035) ±0.200(0.008)
E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED
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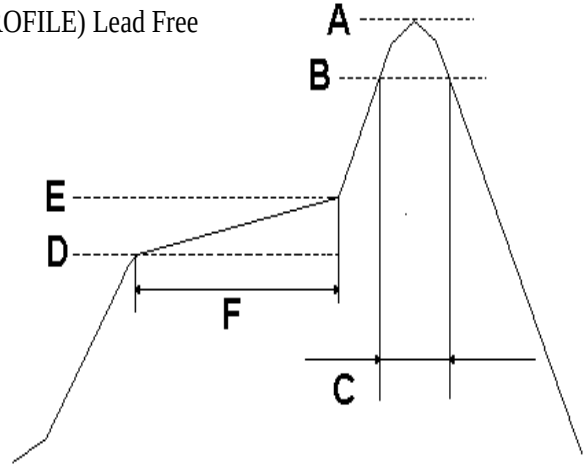
2.-Dimensions are in millimeters (inches)
3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260 ± 5℃*
B	*230± 5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*

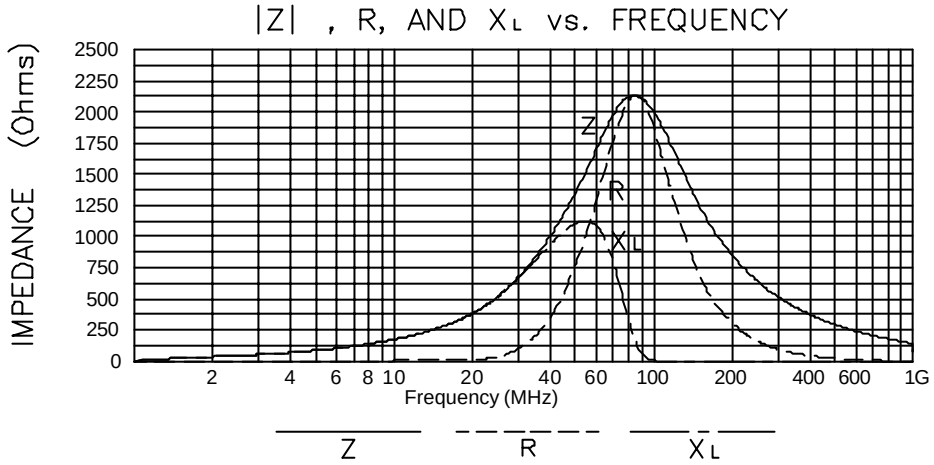


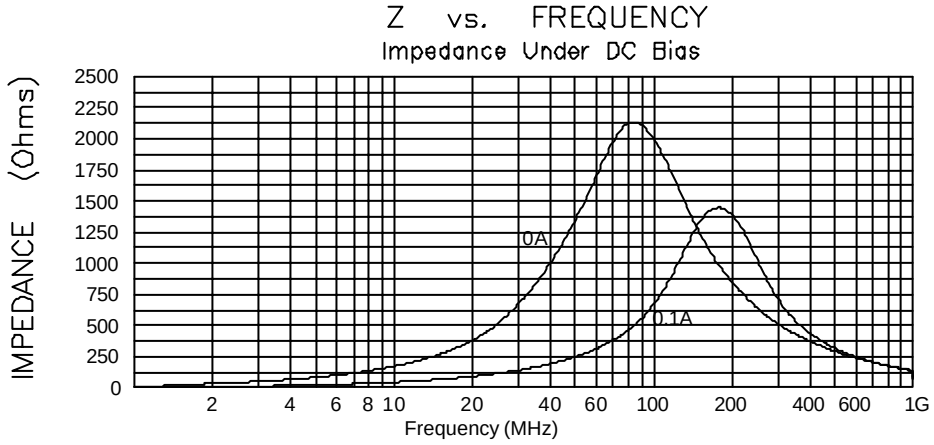
UNCONTROLLED DOCUMENT

BCCB-2012E1-202T

ELECTRICAL CHARACTERISTICS:

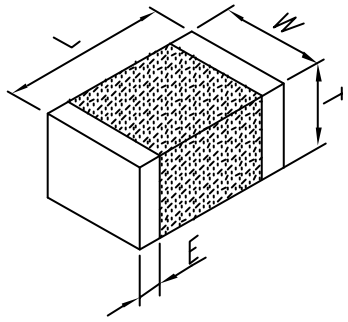
	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	2000		
Minimum	1500		
Maximum	2500	0.80	100mA





Agilent 4291B RF Impedance/Material Analyzer
HP 16192A Fixture

OSC level : 250 mV



PHYSICAL DIMENSIONS:

L 2.00(0.079) ±0.200(0.008)

W 1.25(0.049) ±0.200(0.008)

T 0.90(0.035) ±0.200(0.008)

E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

1.-All edges and corners must be rounded.

2.-Dimensions are in millimeters (inches)

3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	*260±5℃*
B	*230±5℃*
C	*30±10sec*
D	*150℃*
E	*180℃*
F	*90±30sec*